

## High voltage fast-switching NPN power transistor

#### **Features**

- High voltage capability
- Low spread of dynamic parameters
- Low base-drive requirements
- Very high switching speed
- Fully characterized at 125 °C

#### **Applications**

- Electronic transformer for halogen lamps
- Electronic ballast for fluorescent lighting
- Switch mode power supplies.



The BUL810 is manufactured using high voltage multiepitaxial mesa technology for cost-effective high performance. It uses a hollow emitter structure to enhance switching speeds.

The BUL series is designed for use in lighting applications and low cost switch-mode power supplies.

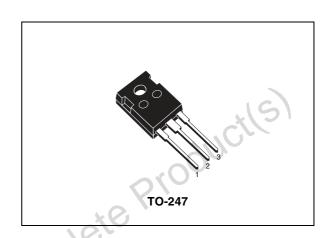


Figure 1. Internal schematic diagram

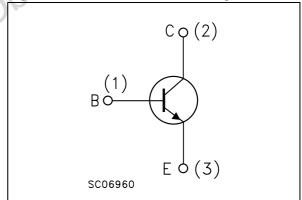


Table 1. Device summary

Order code	Marking	Package	Packaging
BUL810	BUL810	TO-247	Tube

Electrical ratings BUL810

# 1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-emitter voltage (V <sub>BE</sub> = 0)	1000	V
V <sub>CEO</sub>	Collector-emitter voltage (I <sub>B</sub> = 0)	450	V
V <sub>EBO</sub>	Emitter-base voltage (I <sub>C</sub> = 0)	9	V
I <sub>C</sub>	Collector current	15	Α
I <sub>CM</sub>	Collector peak current (t <sub>P</sub> < 5 ms)	22	А
I <sub>B</sub>	Base current	5	Α
I <sub>BM</sub>	Base peak current (t <sub>P</sub> < 5 ms)	10	Α
P <sub>tot</sub>	Total dissipation at T <sub>c</sub> = 25 °C	125	W
T <sub>stg</sub>	Storage temperature	-65 to 150	°C
TJ	Max. operating junction temperature	150	°C

Table 3. Thermal data

	Symbol	Parameter		Value	Unit
	R <sub>thj-case</sub>	Thermal resistance junction-case	max	1	°C/W
	R <sub>thj-amb</sub>	Thermal resistance junction-ambient	max	30	°C/W
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# 2 Electrical characteristics

 $(T_{case} = 25 \, ^{\circ}C \text{ unless otherwise specified})$ 

Table 4. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I <sub>CES</sub>	Collector cut-off current (V <sub>BE</sub> = 0)	V <sub>CE</sub> = 1000 V V <sub>CE</sub> = 1000 V T <sub>C</sub> = 125 °C			100 500	μ <b>Α</b> μ <b>Α</b>
I <sub>CEO</sub>	Collector cut-off current (I <sub>B</sub> = 0)	V <sub>CE</sub> = 450 V			250	μА
V <sub>CEO(sus)</sub> (1)	Collector-emitter sustaining voltage (I <sub>B</sub> = 0)	I <sub>C</sub> = 100 mA	450	40		V
V <sub>EBO</sub>	Emitter-base voltage (I <sub>C</sub> = 0)	I <sub>E</sub> = 10 mA	9			V
V <sub>CE(sat)</sub> (1)	Collector-emitter saturation voltage	$I_C = 5 A$ $I_B = 1 A$ $I_C = 8 A$ $I_B = 1.6 A$ $I_C = 12 A$ $I_B = 2.4 A$			1 1.5 5	V V V
V <sub>BE(sat)</sub> (1)	Base-emitter saturation voltage	I <sub>C</sub> = 5 A I <sub>B</sub> = 1 A I <sub>C</sub> = 8 A I <sub>B</sub> = 1.6 A			1.3 1.6	V V
h <sub>FE</sub> <sup>(1)</sup>	DC current gain	$I_C = 10 \text{ mA}$ $V_{CE} = 5 \text{ V}$ $I_C = 5 \text{ A}$ $V_{CE} = 5 \text{ V}$	10 10		40	
t <sub>s</sub>	Inductive load Storage time Fall time	$\begin{split} I_{C} = 8 \; A & I_{B1} = 1.6 \; A \\ V_{CL} = 350 \; V & L = 200 \; \mu H \\ V_{BE(off)} = -5 \; V & R_{BB} = 0.4 \; \Omega \end{split}$		1.5 55	2.3 110	μs ns
t <sub>s</sub>	Inductive load Storage time Fall time	$\begin{split} I_C = 8 & A & I_{B1} = 1.6 & A \\ V_{CL} = 350 & V & L = 200 & \mu H \\ V_{BE(off)} = -5 & V & R_{BB} = 0.4 & \Omega \\ T_c = 100 & ^{\circ}C & \end{split}$		1.9 80		μs ns

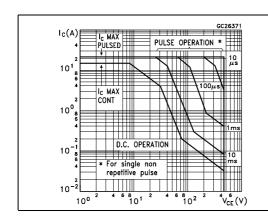
<sup>1.</sup> Pulse duration = 300 μs, duty cycle ≤1.5%

Electrical characteristics BUL810

### 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Derating curve



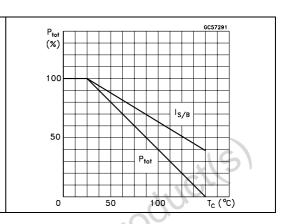
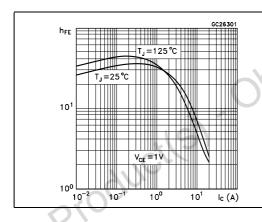


Figure 4. DC current gain

Figure 5. DC current gain



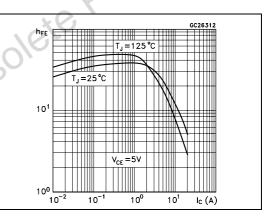
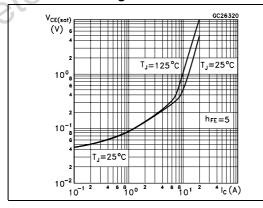
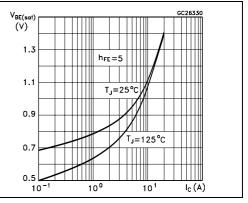


Figure 6. Collector-emitter saturation voltage

Figure 7. Base-emitter saturation voltage



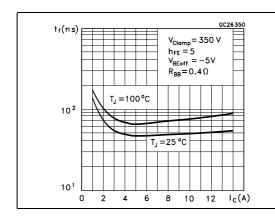


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BUL810 Electrical characteristics

Figure 8. Inductive load fall time

Figure 9. Inductive storage fall time



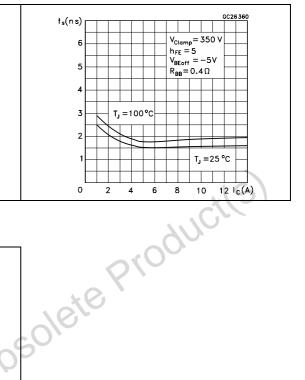
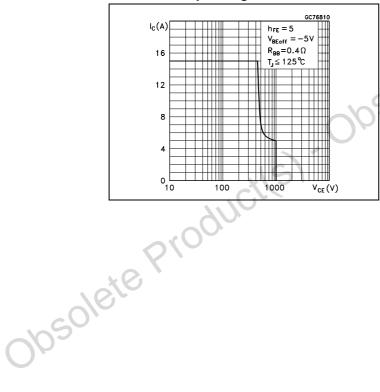


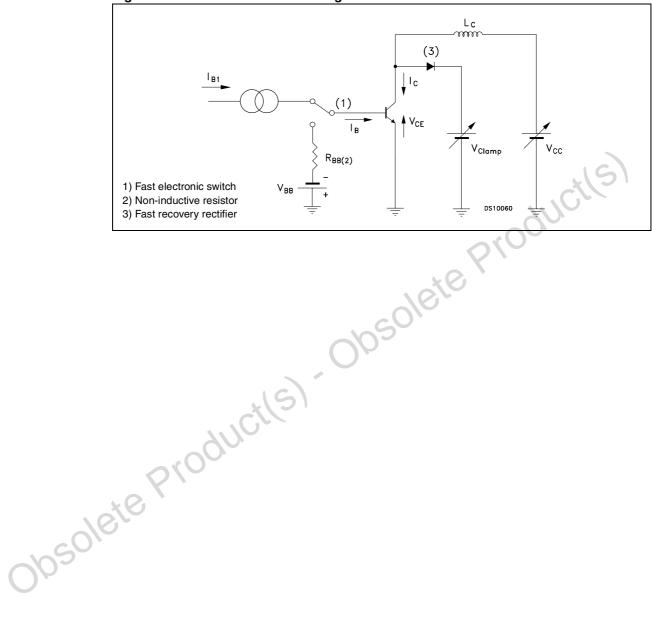
Figure 10. Reverse biased safe operating area



Electrical characteristics BUL810

#### 2.2 Test circuit

Figure 11. Inductive load switching test circuit



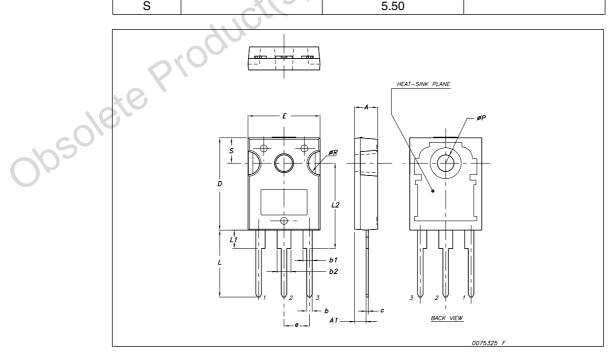
### 3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

Obsolete Product(s). Obsolete Product(s)

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Dim.	mm.				
	Min.	Тур	Max.		
Α	4.85		5.15		
A1	2.20		2.60		
b	1.0		1.40		
b1	2.0		2.40		
b2	3.0		3.40		
С	0.40		0.80		
D	19.85		20.15		
E	15.45	40	15.75		
е		5.45			
L	14.20	60/	14.80		
L1	3.70	200	4.30		
L2		18.50			
øΡ	3.55		3.65		
øR	4.50		5.50		
S		5.50			



BUL810 Revision history

# 4 Revision history

Table 5. Document revision history

Date	Revision	Changes
01-Feb-2003	3	
12-Feb-2008	4	Package change from TO-218 to TO-247.

Obsolete Product(s). Obsolete Product(s)

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